MEETING AGENDA

Spring 2024 – Workshop on Enabling a Resilient US Microelectronics Ecosystem

All sessions are open to the public

Wednesday, April 17, 2024

All times ET

8:30 – 9:00	**BREAKFAST**
9:00 – 9:05	**Welcome**

John Manferdelli, Chair, NASEM Cyber Resilience Forum

9:05 – 10:30 **Panel 1: Security and Assurances Requirements for National Security Applications**

Moderator: **Jay Lewis**, Commerce

Speakers: **Molly Just**, DoD

Meredith Dyck, NSA

Murugiah Souppaya, NIST

Chris Irvine, Qualcomm

Discussion followed by Q&A Session.

10:30 – 11:00 **BREAK**

11:00 – 12:30 **Panel 2: Design and Fabrication Ecosystem Resiliency**

Moderator: **Bob Wisnieff**, IBM

Speakers: **Mike Lyden**, Draper Labs

Catherine (Cait) Crawford, IBM

Steve Carlson, Cadence

Shawn Fetterolf, Intel

Discussion followed by Q&A Session.

12:30 – 1:30	**LUNCH**	
1:30 – 3:00	**Panel 3: Engineering Security into the Supply Chain**	
	Moderator:	**Tim Booher**, Forum Member, Boeing
	Speakers:	**Brett Hamilton**, Applied Research Institute
		Noah Evans, Sandia National Lab
		Wayne Austad, Idaho National Lab
		Jeff Krieg, DoD
		Discussion followed by Q&A Session.

3:00 – 3:30	**BREAK**	
3:30 – 5:00	**Panel 4:**	**Secure Fabrication – requirements and access**
	Moderator:	**John Manferdelli,** Forum Chair
	Speakers:	**John Zolper**, RTX
		Louise Sengupta, Northrup Grumman
		Saverio Fazzari, Booz Allen Hamilton
		Discussion followed by Q&A Session.

5:00 – 5:45	**Panel 5: Summary Discussion (session moderators)**	
	Speakers:	**Jay Lewis**, Commerce
		Bob Wisnieff, IBM
		Tim Booher, Boeing
		John Manferdelli, Forum Chair

5:45 – 7:00	**Reception**	